



ABSTRACT

A laminate which is advantageously used as an insulating layer for electronic package application and as an adhesive film for fixing a semiconductor wafer for semiconductor device application, laminates comprising the same and a process for manufacturing the above laminate. The laminate (I) comprises a base layer (A) and an adhesive layer (B) formed on one side or both sides of the layer A, the layer A is a film made of (A-1) a specific wholly aromatic polyimide (PI^{A-1}) or (A-2) a specific wholly aromatic polyamide (PA^{A-2}); and the layer B comprises (B-1) a specific wholly aromatic polyimide (PI^{B-1}), (B-2) a specific wholly aromatic polyamide (PA^{B-2}), or (B-3) a specific resin composition (RC^{B-3}) comprising a wholly aromatic polyimide (PI^{B-3}) and a specific wholly aromatic polyamide (PA^{B-3}), laminates comprising the same and a process for manufacturing the above laminate.